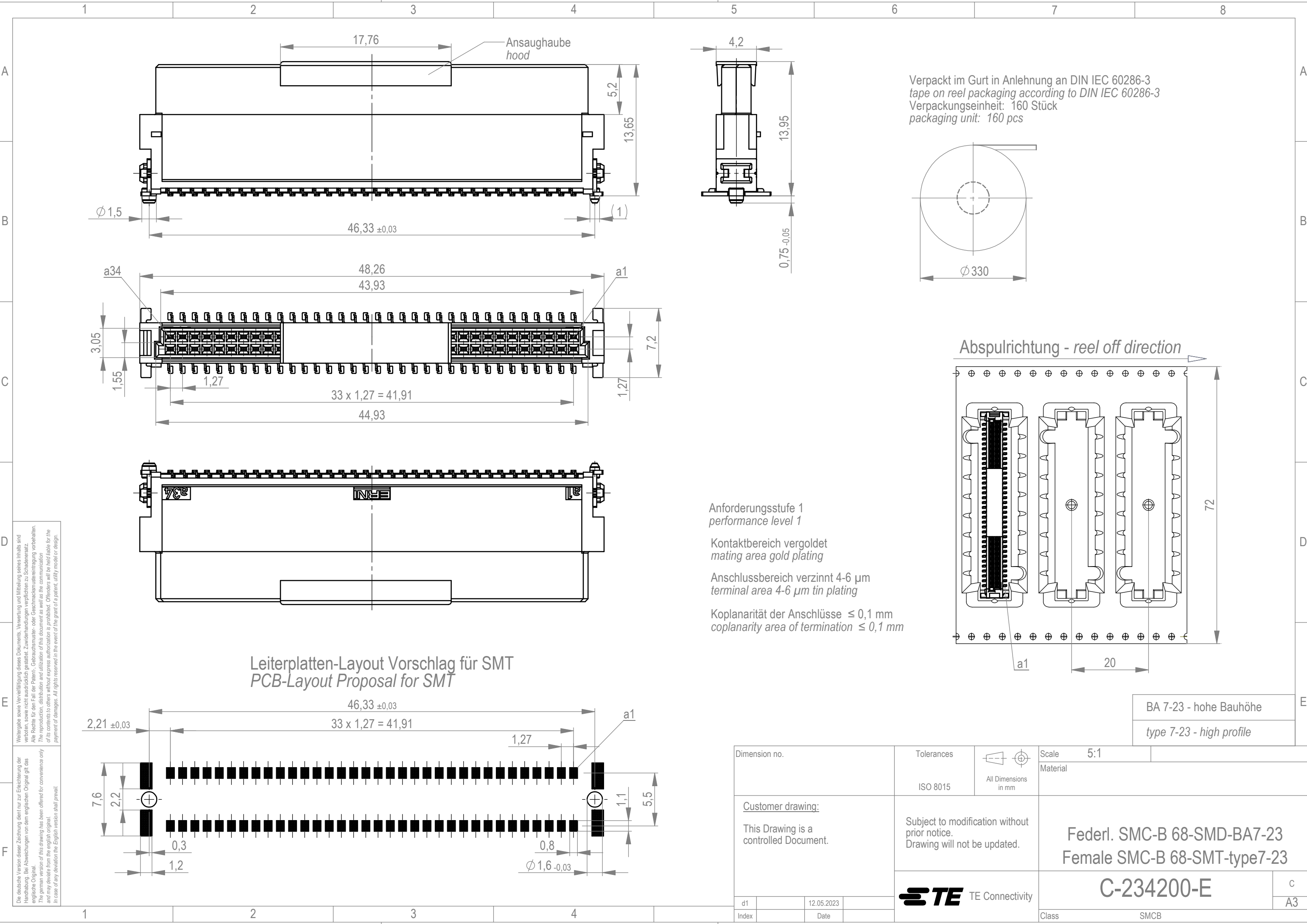




Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT

Anforderungsstufe 1
performance level 1

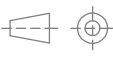
Kontaktbereich vergoldet
mating area gold plating

Anschlussbereich verzinkt 4-6 µm
terminal area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm

Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 160 Stück
packaging unit: 160 pcs

BA 7-23 - hohe Bauhöhe
type 7-23 - high profile

Dimension no.				Tolerances				Scale		5:1									
				ISO 8015		All Dimensions in mm		Material											
<u>Customer drawing:</u> This Drawing is a controlled Document.				Subject to modification without prior notice. Drawing will not be updated.				Federl. SMC-B 68-SMD-BA7-23 Female SMC-B 68-SMT-type7-23											
<table><tr><td>d1</td><td></td><td>12.05.2023</td><td></td></tr><tr><td>Index</td><td></td><td>Date</td><td></td></tr></table>				d1		12.05.2023		Index		Date		 TE Connectivity				C-234200-E			C
d1		12.05.2023																	
Index		Date																	
							A3												
				Class				SMCB											